



Layer	Stack up	Description	Finish Thickness	Isolation Distance	Copper Coverage	εr		
1		Taiyo PSR 2000				4.000		
		Copper Foil 12 microns	1.674		100.000			
		EM827B Prepreg 1080	3.050	2.866		3.670		
		EM827B Prepreg 2113	3.850	3.618		3.870		
2			1.260		67.000			
3		EMC827 47 mil core 1/1	44.240	44.240		4.280		
4			1.260		66.000			
		EM827B Prepreg 2113	3.850	3.611		3.870		
		EM827B Prepreg 1080	3.050	2.861		3.670		
		Copper Foil 12 microns	1.674		100.000			
		Taiyo PSR 2000				4.000		

Copper Thickness = 5.867 |Dielectric Thickness = 57.196 |Overall Processed Thickness = 63.063 |

Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width	Trace Separation	Lower Ground Strip Width	Upper Ground Strip Width	Ground Strip Separation	Broadside 2nd Layer	Trace Offset	Calculated Impedance	Target Impedance	Tol (+/- %)	
Edge Coupled Coated Microstrip 2B	1	2	0	5.000	9.070	0.000	0.000	0.000	0	0.000	120.010	120.000	10.000	

Notes

StackName: hcl-towermountamplifierunit-rev10	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1	
Date: 03/12/2k12	Associated Documents:						
Author:	CAM No: F01122k12-23629						
Department:							
Site:							